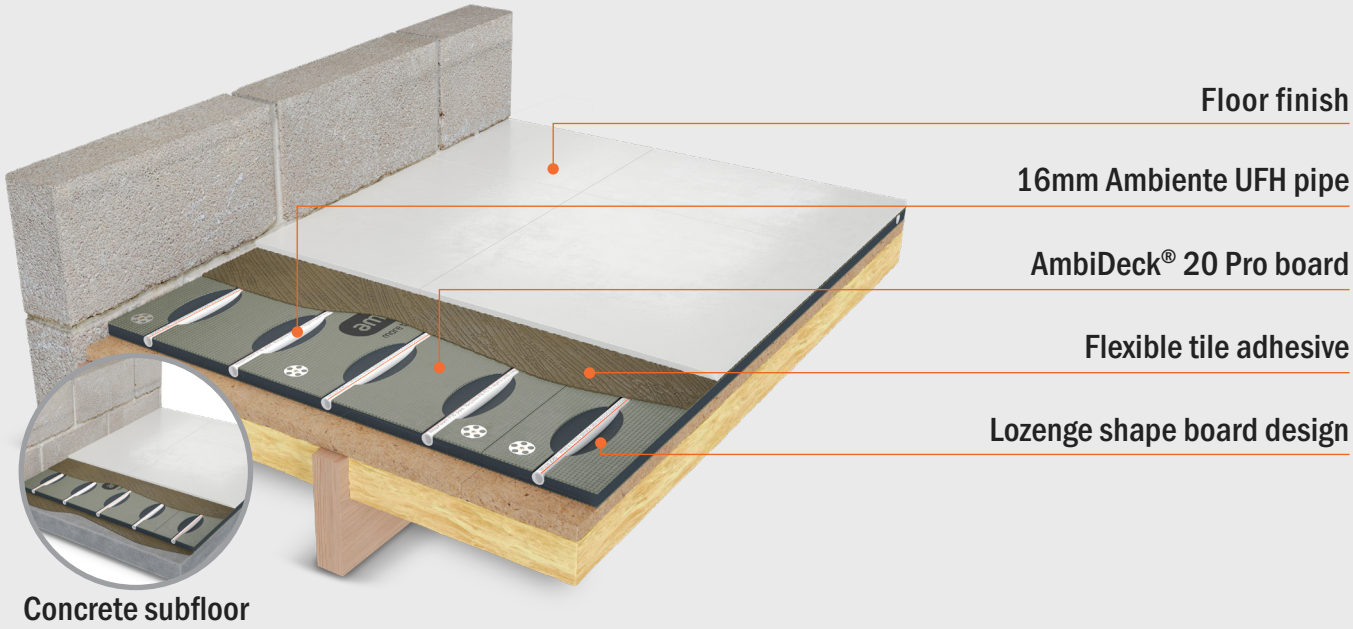
AmbiDeck® 20 Pro Datasheet



20MM
Low-profile build-up

Tile over directly

High thermal insulation material

Lightweight

System Overview

The AmbiDeck® 20 Pro system really does give the best of both worlds - it provides a low-profile Underfloor Heating system, which incorporates an insulation layer and can be tiled directly. AmbiDeck® 20 Pro consists of a high-density XPS insulation panel that is 20 mm thick.

The face of the panel is cement-coated, making it rigid and durable. It's designed with unique lozenge-shaped cut-outs to take 16 mm UFH pipework, with a 150 mm radius return grooved into each panel. Additional pipework channels can easily be routed/grooved into the panel.

Key Features

- **Low-profile** - 20mm build-up
- **Unique lozenge-shaped board design** - +10% output
- **Enhanced thermal conductivity** - 0.031 W/mK
- **Recycled carbon** - Improved thermal conductivity
- **3 board design options** - Standard panel, corner panel, and highway panel

Installation Overview

AmbiDeck® 20 Pro must be laid onto a flat, level subfloor, either concrete or timber-based. Over a concrete floor, we recommend adhering panels with flexible tile adhesive or DeckBond spray adhesive. Over a timber floor, we recommend securing the panels down with a minimum of 12 AmbiDeck® screws & washers per board, or alternatively with DeckBond spray adhesive.

Tiling can be laid directly over the system - we recommend priming the boards with a tiling primer and filling any gaps with flexible tiling adhesive. If laying carpet/vinyl/wooden floor, we recommend a minimum of 6 mm levelling compound over the top of AmbiDeck® 20 Pro.

PATENT PENDING

PERFORMANCE SPECIFICATION		
20°C ROOM TEMPERATURE AT MWT OF 45°C AND 0 TOG		
HEIGHT (MM)	WEIGHT (KG/M²)	OUTPUT (W/M²)
20	15	120

Tested in accordance with BS EN1264-2:2021